L Number	Hits	Search Text	DB	Time stamp
1	17505	interconnect$3 and ((passivation or oxide or nitride) with (thermal or heat$3 or anneal$3))	USPAT; US-PGPUB	2004/07/30 16:08
2	4147	wire and "bond pad"	USPAT; US-PGPUB	2004/07/30 13:47
3	266	(interconnect$3 and ((passivation or oxide or nitride) with (thermal or heat$3 or anneal$3))) and (wire and "bond pad")	USPAT; US-PGPUB	2004/07/30 13:48
5	75320	@ad>20030624 or @rlad>20030624	USPAT; US-PGPUB	2004/07/30 13:48
6	234	((interconnect$3 and ((passivation or oxide or nitride) with (thermal or heat$3 or anneal$3))) and (wire and "bond pad")) not (@ad>20030624 or @rlad>20030624)	USPAT; US-PGPUB	2004/07/30 13:48
7	2	(((interconnect$3 and ((passivation or oxide or nitride) with (thermal or heat$3 or anneal$3))) and (wire and "bond pad")) not (@ad>20030624 or @rlad>20030624)) and "probe test"	USPAT; US-PGPUB	2004/07/30 15:29
8	147873	grind$3	USPAT; US-PGPUB	2004/07/30 16:09
9	71	(((interconnect$3 and ((passivation or oxide or nitride) with (thermal or heat$3 or anneal$3))) and (wire and "bond pad")) not (@ad>20030624 or @rlad>20030624)) and grind$3	USPAT; US-PGPUB	2004/07/30 15:51
10	3444	"probe test"	USPAT; US-PGPUB	2004/07/30 15:51
11	0	((((interconnect$3 and ((passivation or oxide or nitride) with (thermal or heat$3 or anneal$3))) and (wire and "bond pad")) not (@ad>20030624 or @rlad>20030624)) and grind$3) and "probe test"	USPAT; US-PGPUB	2004/07/30 15:51
12	25	(interconnect$3 and ((passivation or oxide or nitride) with (thermal or heat$3 or anneal$3))) and "probe test"	USPAT; US-PGPUB	2004/07/30 15:51
13	24	((interconnect$3 and ((passivation or oxide or nitride) with (thermal or heat$3 or anneal$3))) and "probe test") not (@ad>20030624 or @rlad>20030624)	USPAT; US-PGPUB	2004/07/30 15:53
14	78	"probe test" and grind$3	USPAT; US-PGPUB	2004/07/30 15:54
15	559066	interconnect$3	USPAT; US-PGPUB	2004/07/30 15:54
16	20	("probe test" and grind$3) and interconnect$3	USPAT; US-PGPUB	2004/07/30 15:54
17	171800	438/$.ccls. or 257/$.ccls.	USPAT; US-PGPUB	2004/07/30 15:55
18	8	(("probe test" and grind$3) and interconnect$3) and (438/$.ccls. or 257/$.ccls.)	USPAT; US-PGPUB	2004/07/30 16:08
19	1441	438/for.343.ccls.	EPO; JPO; DERWENT; IBM_TDB	2004/07/30 16:08
20	752	interconnect$3 and ((passivation or oxide or nitride) with (thermal or heat$3 or anneal$3))	EPO; JPO; DERWENT; IBM_TDB	2004/07/30 16:08
21	0	438/for.343.ccls. and (interconnect$3 and ((passivation or oxide or nitride) with (thermal or heat$3 or anneal$3)))	EPO; JPO; DERWENT; IBM_TDB	2004/07/30 16:08
23	0	(interconnect$3 and ((passivation or oxide or nitride) with (thermal or heat$3 or anneal$3))) and (grind$3 and "probe test")	EPO; JPO; DERWENT; IBM_TDB	2004/07/30 16:09
22	4	grind$3 and "probe test"	EPO; JPO; DERWENT; IBM_TDB	2004/07/30 16:09
-	122124	grinding	USPAT; US-PGPUB	2004/07/28 17:38
-	1076	438/612.ccls.	USPAT; US-PGPUB	2004/07/28 17:48
-	99385	sintering or baking	USPAT; US-PGPUB	2004/07/28 18:01
-	15847	grind$3 and (sintering or baking)	USPAT; US-PGPUB	2004/07/28 17:39
-	13	(grind$3 and (sintering or baking)) and (wire and "bond pad")	USPAT; US-PGPUB	2004/07/28 17:41
-	7	(grind$3 and (sintering or baking)) and 438/612.ccls.	USPAT; US-PGPUB	2004/07/28 17:41

-	7	((grind$3 and (sintering or baking)) and 438/612.ccls.) not ((grind$3 and (sintering or baking)) and (wire and "bond pad"))	USPAT; US-PGPUB	2004/07/28 17:44
-	7	grinding and 438/612.ccls. and (wire and "bond pad")	USPAT; US-PGPUB	2004/07/28 17:48
-	7	grind$3 and 438/612.ccls. and (wire and "bond pad")	USPAT; US-PGPUB	2004/07/28 17:48
-	1020	438/613.ccls.	USPAT; US-PGPUB	2004/07/28 17:49
-	275	grind$3 and (wire and "bond pad")	USPAT; US-PGPUB	2004/07/28 17:48
-	4	438/613.ccls. and (grind$3 and (wire and "bond pad"))	USPAT; US-PGPUB	2004/07/28 17:48
-	559	438/614.ccls.	USPAT; US-PGPUB	2004/07/28 18:01
-	3	grind$3 and ((wire and "bond pad") and 438/614.ccls.)	USPAT; US-PGPUB	2004/07/28 17:50
-	98	(wire and "bond pad") and 438/614.ccls.	USPAT; US-PGPUB	2004/07/28 17:50
-	298	438/617.ccls.	USPAT; US-PGPUB	2004/07/28 18:05
-	0	grind$3 and (sintering or baking) and 438/617.ccls.	USPAT; US-PGPUB	2004/07/28 18:01
-	270559	sinter$3 or bak$3	USPAT; US-PGPUB	2004/07/28 18:01
-	23	438/617.ccls. and (sinter$3 or bak$3)	USPAT; US-PGPUB	2004/07/28 18:02
-	511	438/977.ccls.	USPAT; US-PGPUB	2004/07/28 18:05
-	56	(sinter$3 or bak$3) and 438/977.ccls.	USPAT; US-PGPUB	2004/07/28 18:05
-	25	grind$3 and ((sinter$3 or bak$3) and 438/977.ccls.)	USPAT; US-PGPUB	2004/07/28 18:09
-	1560309	heat$3 or thermal or anneal$3	USPAT; US-PGPUB	2004/07/28 18:10
-	180382	(sinter$3 or bak$3) and (heat$3 or thermal or anneal$3)	USPAT; US-PGPUB	2004/07/28 18:11
-	413	(wire and "bond pad") and ((sinter$3 or bak$3) and (heat$3 or thermal or anneal$3))	USPAT; US-PGPUB	2004/07/30 12:16
-	2	(("6734968") or ("6694284")).PN.	USPAT; US-PGPUB	2004/07/30 13:45